Imaging Ellipsometry for full wafer analysis of Graphene and hexagonal Boron-Nitride

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Imaging ellipsometry (IE) combines the resolution of an optical microscope with the sensitivity of ellipsometry for thin films. It allows to measure monolayers of 2Dmaterials but also visualize these to substrates. monolayers on arbitrary - It overcomes the need of specially tuned SiO₂ thicknesses to visualize e.g. Graphene in an optical microscope.

In the talk we present [1], that IE is able to characterize Graphene throughout all stages of the manufacturing process from the growth on Cu-foil up to the transferred sample on Si wafers. Unlike other methods we can directly visualize graphene on the rough Cu. Figure 1 shows a large area map of Graphene on Cu. The Graphene is directly characterized on the Cu-foil, no oxidation of the Cu is needed. To overcome the waviness of the foil, an autofocus algorithm is developed and applied.

Figure 2 shows a Graphene monolayer and hBN monolayer after the transfer process to a Si/SiO_2 substrate. The contrast mode of IE is able to distinguish the different regions: (a) substrate only, (b) hBN only, (c) Graphene only and (d) an overlapping region of hBN and Graphene. The complete sample approx. 1 cm x 0.8 cm is recorded in less than 6 minutes and shows defects and wrapping of hBN of a size as small as 4 µm.

Lastly, we demonstrate that this method can be used to characterise full 4'' wafers of graphene on Si within short time spans at 4 µm resolution.

References

Figures



Figure 1: IE measurement of graphene on Cu prior to oxidation



Figure 2: hBN and Graphene monolayer on Si/SiO₂ substrate. Visualized in less than 6 minutes. (a) substrate only, (b) hBN only, (c) Graphene only and (d) monolayer graphene on monolayer hBN.

^[1] Braeuninger, Funke, et al. submitted.